

Silicone Thermal Putty Pad / XK-P60-Putty

Introduction

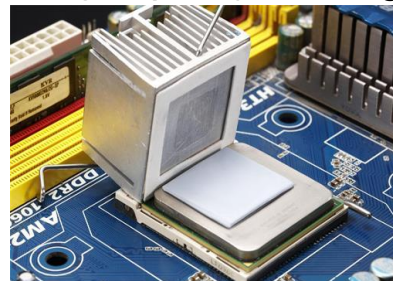
High thermal performance and reliability for irregular surface, excellent flowability and gap filling capacity under low bearing capacity and high compressive load

Features

High reliability

High compressibility

Low bearing capacity



1. Product properties

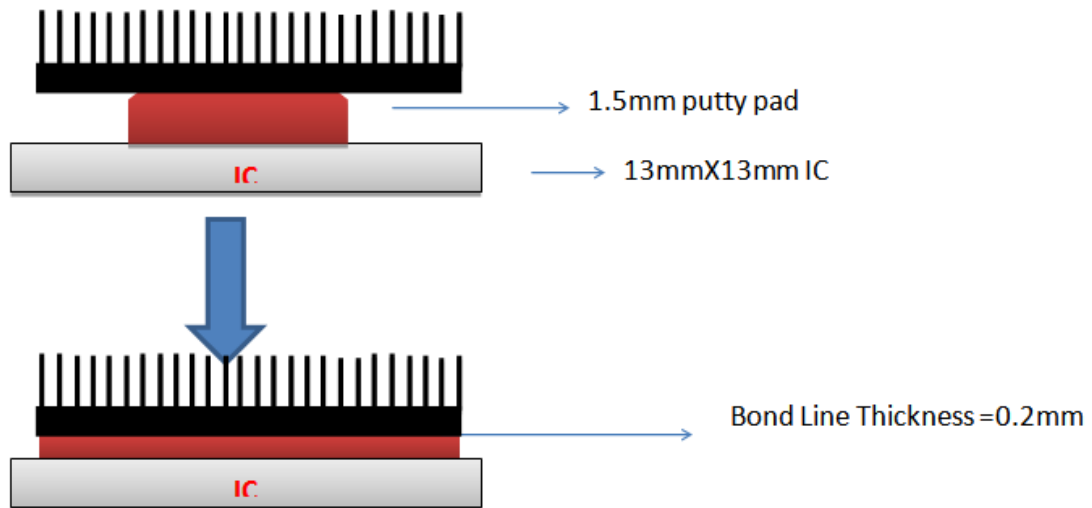
	XK-P60-P	Unit	Test Method
Thickness	1.0/ 1.5	mm	
Color	DarkRed		Visual
Construction	Silicone		
Op. temp. range	-45~150	°C	
Density	3.2	g/cm3	ASTM D792
Thermal Conductivity	6.0	W/mK	ASTM D5470
Breakdown Voltage	>10	KV/mm	ASTM D149
Volume Resistance	10 ¹⁰	Ohm-cm	ASTM D257
Total Mass Loss	<0.4%	%	ASTM E595
Tensile strength	Na	Psi	ASTM D412
Elongation	Na	%	ASTM D412
Flame Rating	V-0		UL-94
REACH/RoHS Compliant	Yes		REACH/ RoHS

2. Thermal properties

	XK-P60-P
RA	Kin2/W
compress 30%	0.24
compress 40%	0.22
compress 50%	0.20
compress 70%	0.15
compress 90%	0.12

3. The Compression Load

	XK-P60-P
	Pressure(psi)
compress 30%	11
compress 40%	27
compress 50%	46
compress 70%	56
compress 90%	77



$$\begin{aligned}
 x &= \sqrt{(BLT \times IC \text{ Area}) / 1.5mm} \\
 &= \sqrt{(0.2mm \times 13mm \times 13mm) / 1.5mm} \\
 &= 4.7
 \end{aligned}$$

USE 5mm X 5mm @ 1.5mm Thickness